

Product Specification 108-57481

12-Nov-2010 Rev O1

USB CONNECTOR, A SERIES, STACKED.

1. SCOPE

This specification covers performance, tests and quality requirements for **USB CONNECTOR, A SERIES, STACKED.**

2. APPLICABLE DOCUMENT

The following documents form a part of this specification to the extent specified herein. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence.

Test Report : 501-57557.

3. **REQUIREMENTS**

3.1. DESIGN AND CONSTRUCTION

Product shall be of the design, construction and physical dimensions specified on the applicable product drawing.

3.2. MATERIALS

- A. Housing: Thermoplastic Glass fiber filled UL 94V-0 rated.
- B. Contact: Copper Alloy, Gold plating on contact area, Tin plated on soldertails, Nickel underplated all over.
- C. Shell: Brass, Nickel plated over Cu underplated all over.

3.3. RATINGS

- A. Current Rating: 1.5 A
- B. Voltage Rating: 250 VDC
- C. Operating temperature: -55° C to $+85^{\circ}$ C.

3.4. TEST CONDITION

The product is designed to meet the electrical, mechanical and environmental performance requirements specified in Figure 1.

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3.5. TEST REQUIREMENTS AND PROCEDURES SUMMARY

TEST DESCRIPTION REQUIREMENT		PROCEDURED			
Examination of product	Meets requirements of product drawing and AMP Specification.	Visual inspection No physical damage			
	ELECTRICAL				
Contact Resistance $30m\Omega$ Max.		EIA- 364-23A			
Insulation Resistance	500MΩ Min.	EIA- 364-21B			
Dielectric Withstanding	No creeping discharge or	EIA- 364-20A			
Voltage	flashes	500VAC for 1 minute applied between			
_	occur.	adjacent contacts.			
Contact Capacitance	2PF Max	EIA 364-30 1 KHz.			
	MECHANICAL				
Durability	No mechanical defects after	EIA- 364-09			
	5000 cycles.	Mated and unmated connector			
		assemblies for 5000 cycles at			
		maximum rate of 200 cycles per hour.			
Mating Force	35 N Max	EIA- 364-13A			
Linmating Force	10N Min	The test speed should be 20mm/min. EIA- 364-13A			
Unmating Force		The test speed should be 20mm/min.			
Random Vibration	10~2000 Hz no current	EIA 364-28 Test Condition V Test			
	interruption greater than 1	Letter A			
	microsecond discontinuity.				
Physical Shock	No current interruption greater than 1 microsecond discontinuity	EIA 364-27 Test Condition H			
Cable Pull-out Force	40 Newton to the cable for 1 minute.	EIA 364-38			
	ENVIRONMENTAL				
Humidity	See note 1.	EIA 364-31 test condition A method III,			
		168hours minimum (seven complete			
		cycles)			
Thermal Shock	See note 1.	EIA- 364-32, 10 cycles -55℃ to +85℃.			
Temperature Life	See note1.	EIA 364-17 Test Condition 3 Method			
		A, 85℃ for 250hours			
	PHYSICAL				
Solderability	See note 1.	MIL-STD-202F Method 208G.			
	95% Min coverage.	Test temperature : 245±5℃.			
		Dip tails into flux for 5 second, drain,			
		and then dip into the solder pot and			
Depistones To Coldoning	Saa pata 1	keep for 5 seconds.			
Resistance To Soldering Heat	See note 1.	MIL-STD-202F METHOD 210B			
IICAL		Product on board test temperature: $260\pm5^{\circ}$ C for 10 seconds.			
Mixed Flowing Gas See note1.		EIA 364-65 Class II Exposures			
ININEU FIUWING GAS		LIA JU4-UJ Class II EXPUSULES			

Figure 1

NOTE1: Shall meet visual requirements, show no physical damages.



3.6. PRODUCT QUALIFICATION AND REQUALIFICATION TEST SEQUENCE

	Test Group						
Test or Examination	Α	В	С	D	E	F	
	Test Sequence (a)						
Examination of Product	1,10	1,5	1,7	1,9	1,3	1,3	
Contact Resistance	3,7	2,4	2,4,6				
Insulation Resistance				3,7			
Dielectric Withstanding Voltage				4,8			
Contact Capacitance				2			
Durability	4						
Mating Force	2						
Unmating Force	8						
Random Vibration	6						
Physical Shock	5						
Cable Pull-out Force	9						
Humidity				6			
Thermal Shock				5			
High Temperature Life		3					
Solderability					2		
Resistance to Soldering Heat						2	
Mixed Flowing Gas			3,5				

Figure 2

NOTE : (a) Numbers indicate sequence in which tests are performed.